

Passive Adaptors to test power delivery network to Zynq UltraScale+ ZU19-C1760 series FPGA's

ProGrAnalog Corp.

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Ver 2.0

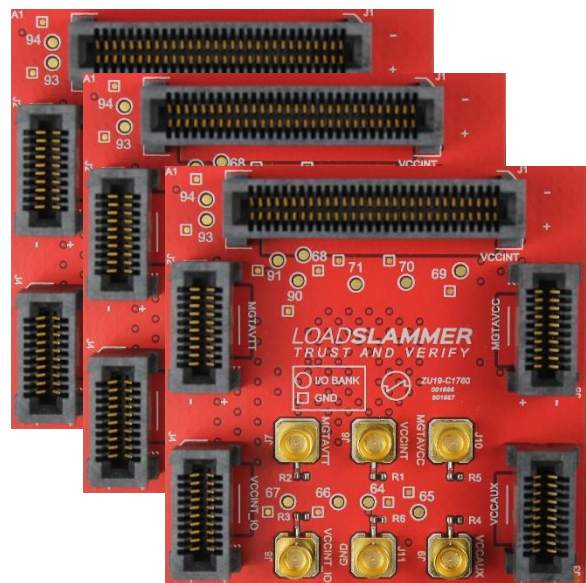
Features

- Set of 3 Passive Adaptors (PA) for PDN testing AMD Xilinx Zynq UltraScale+ ZU19-C1760 series FPGAs
- 5 Samtec connectors to slam: VCCINT, MGTAVCC, VCCAUX, VCCINT_IO, MGTAVTT.
- 6 SMP connectors for testing: MGTAVTT, VCCINT, MGTAVCC, VCCAUX, VCCINT_IO, GND.
- PA with BGA footprint reflows onto ZU19-C1760 PCB pads.
- Remote Vsense on Samtec connectors and SMP mini connectors.
- Most rails can be tested with an LSP200 controller.
- GUI supports transient, pulse train, impedance and 3D plots.

Typical Test Setup

- Passive Adaptor reflowed onto the test board.
- LSP1000RS connected into VCCINT connector.

Pack of 3 Zynq UltraScale+ ZU19-C1760 PA's



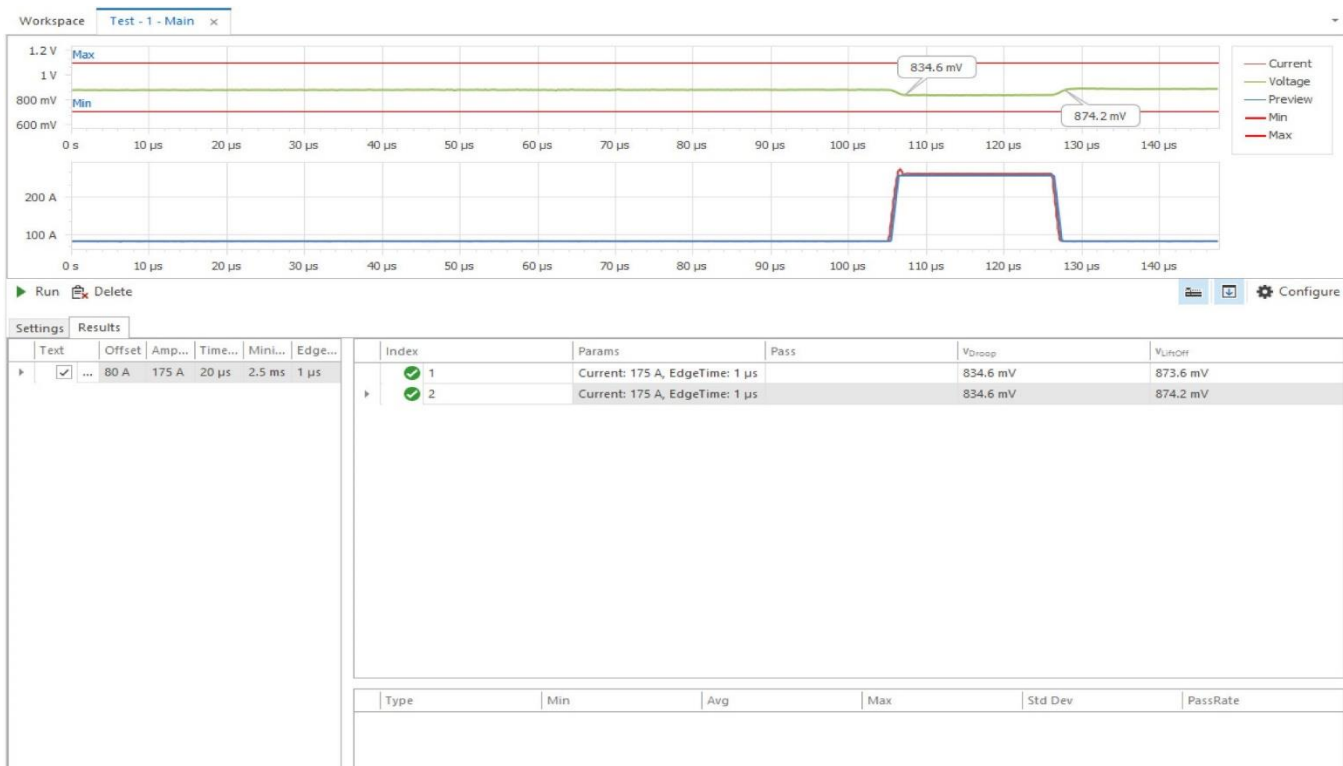
LoadSlammer GUI

Workspace **Test - 1** x

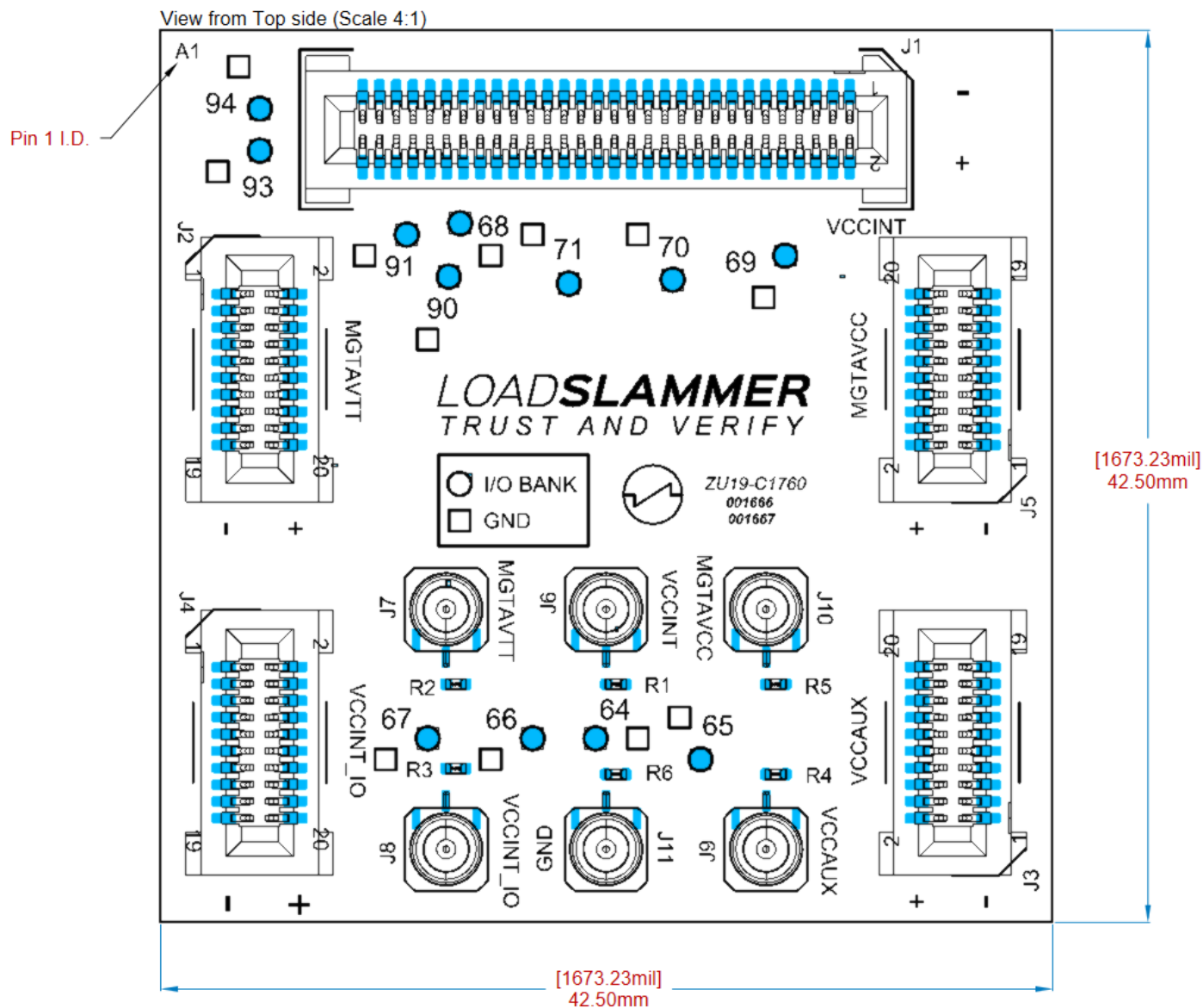
Available Tests Name: Test - 1 Rail: None

- Transient Test**
Transient load step with adjustable rise times, current, and pulse width.
- Pulse Train**
Repeating load steps with a configurable frequency and duty cycle.
- Impedance (Z)**
Large signal output impedance with adjustable current amplitude and offset.
- DC Load**
DC Load with timer.
- Delay**
Timed delay.

Transient test

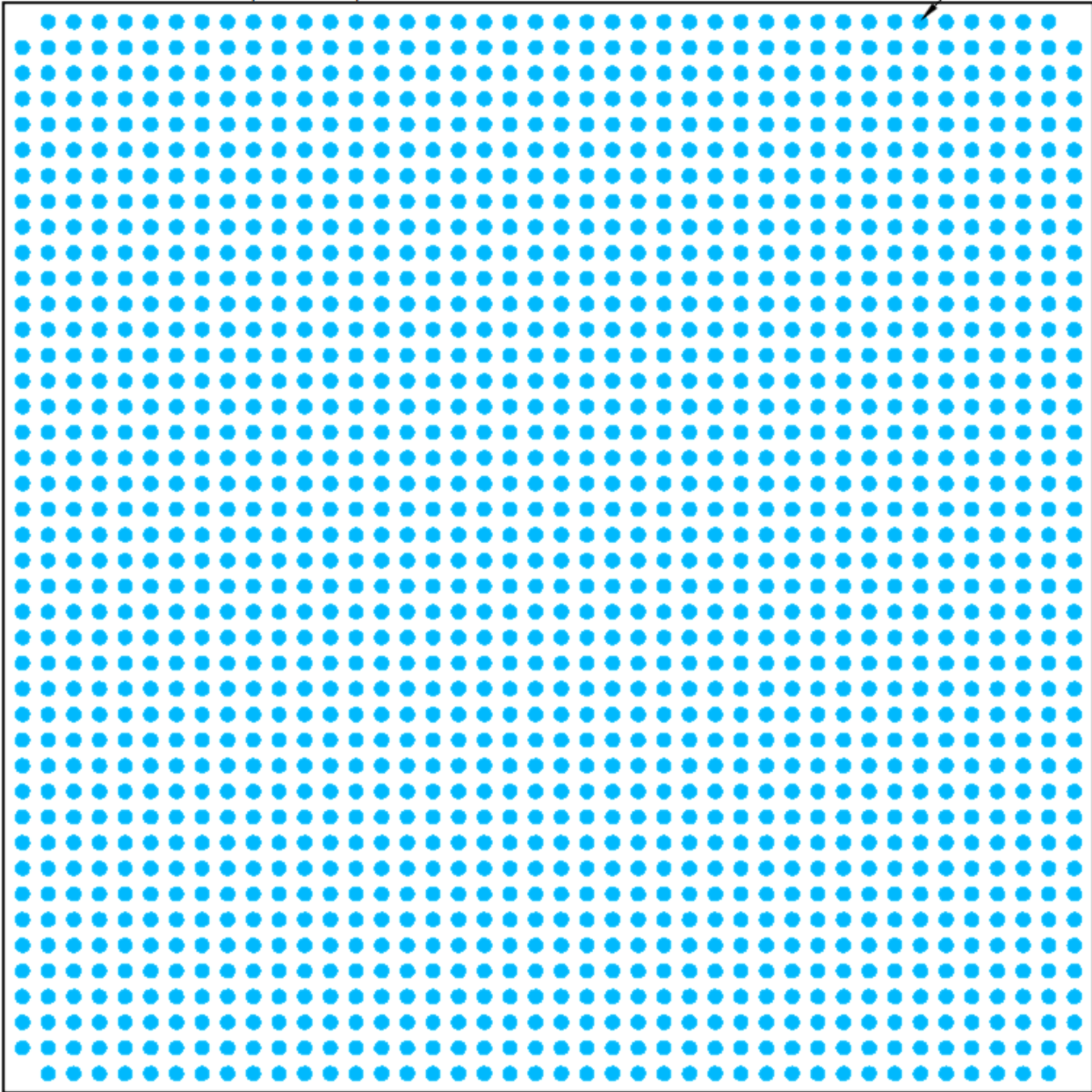


Mechanical Specs



View from Bottom side (Scale 4:1)

1mm BGA Pitch



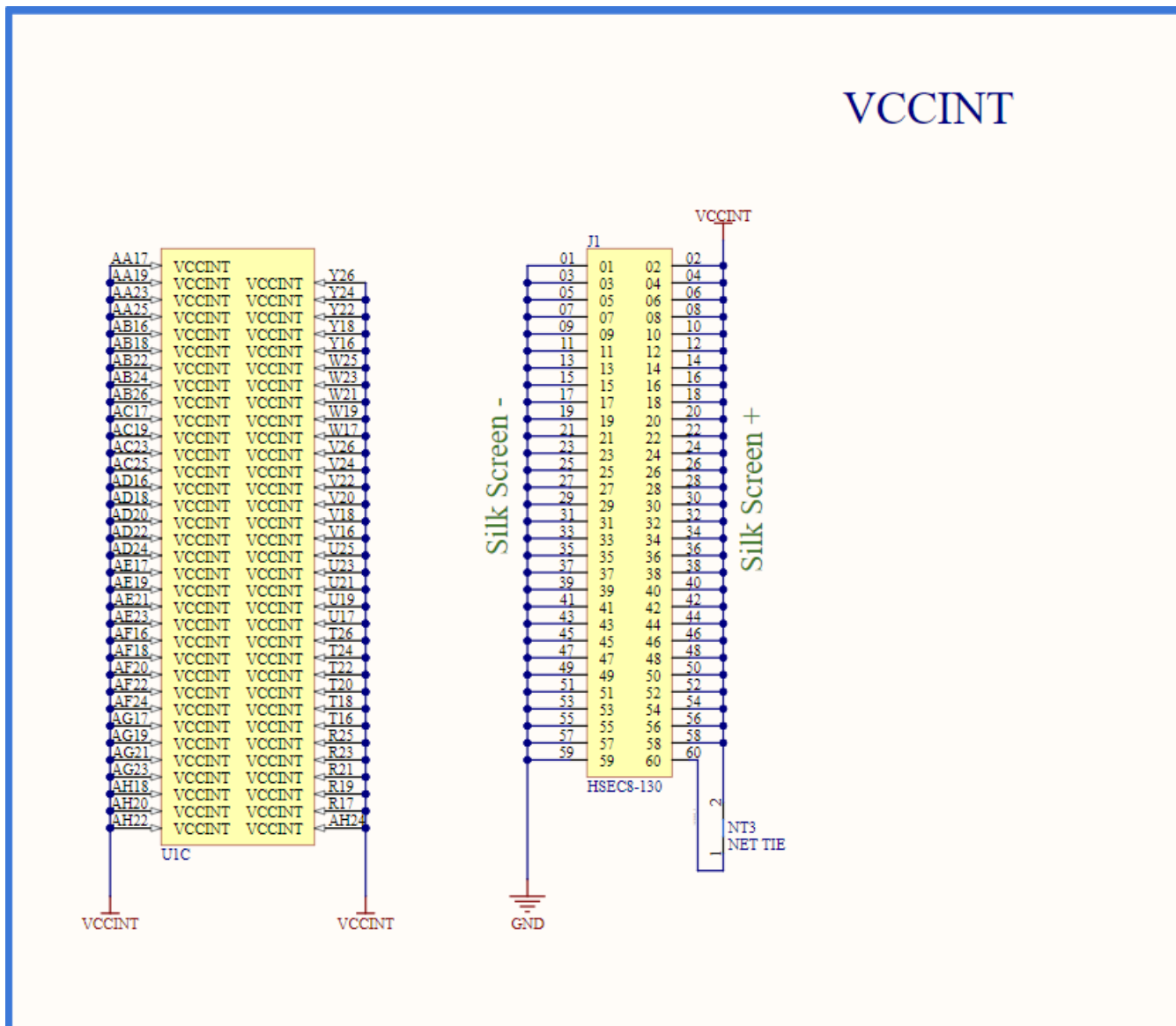
Packing Tray Specs

56.57mm x149.80mm x14.6mm

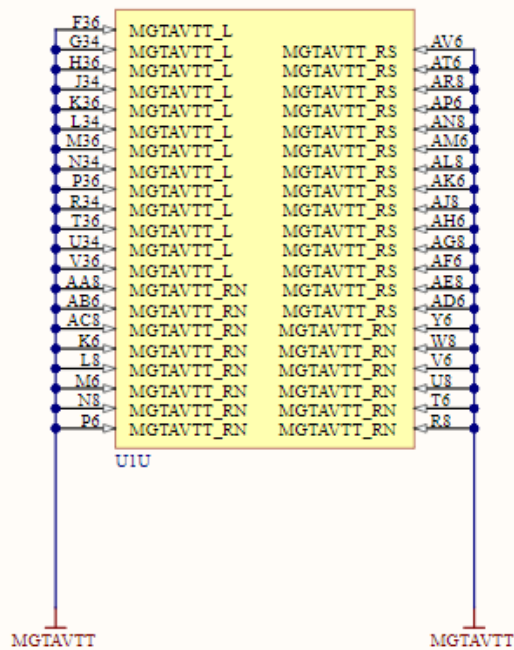
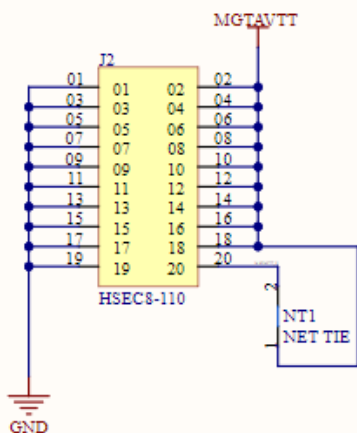
A1 - top left corner



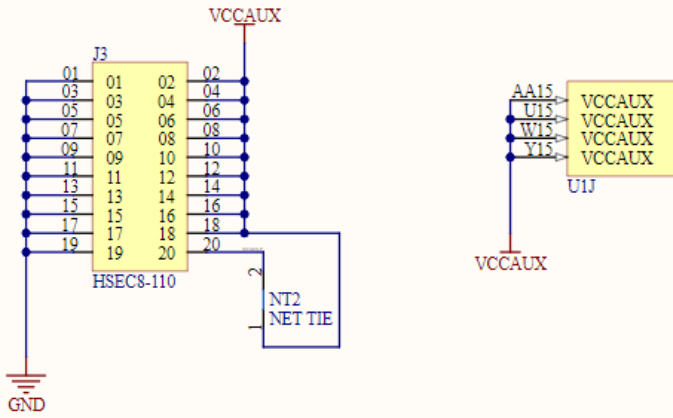
Schematics



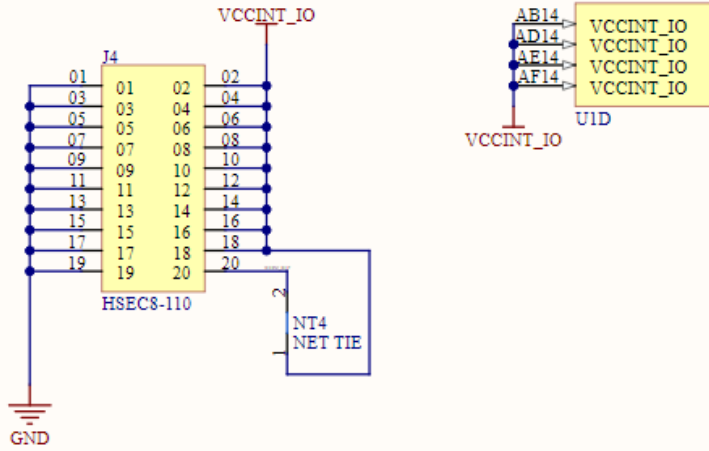
MGTAVTT



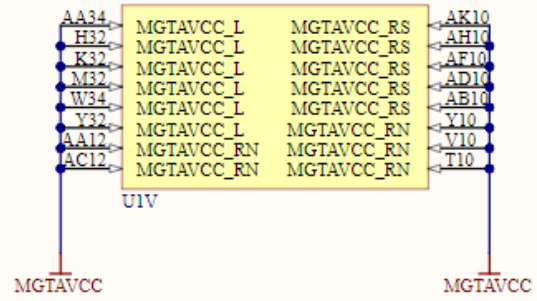
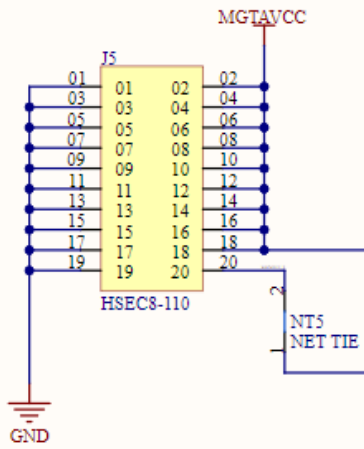
VCCAUX

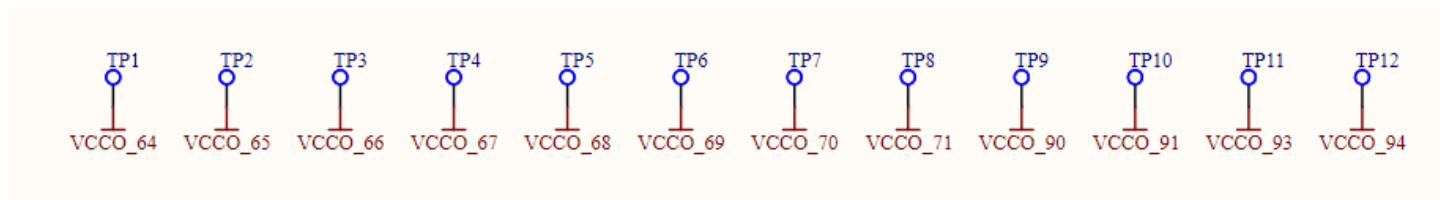
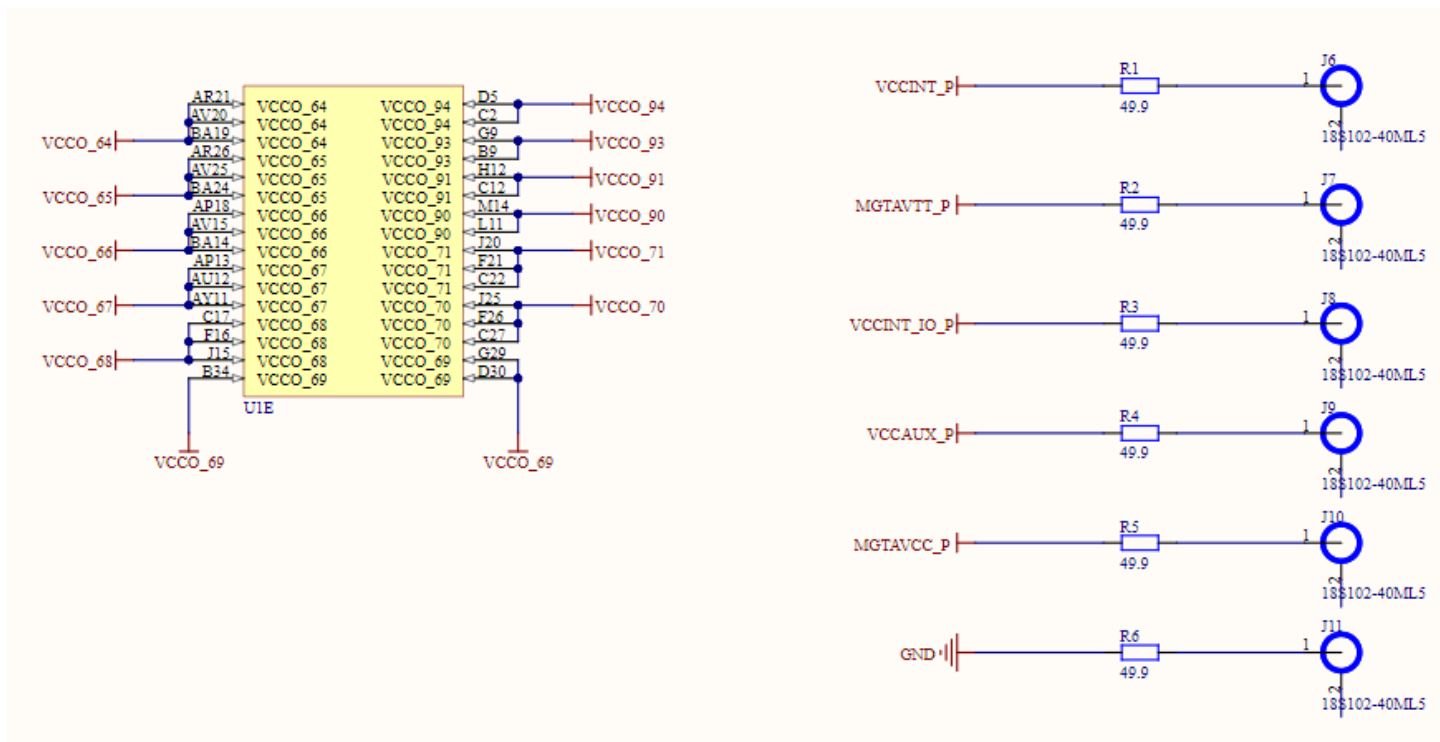


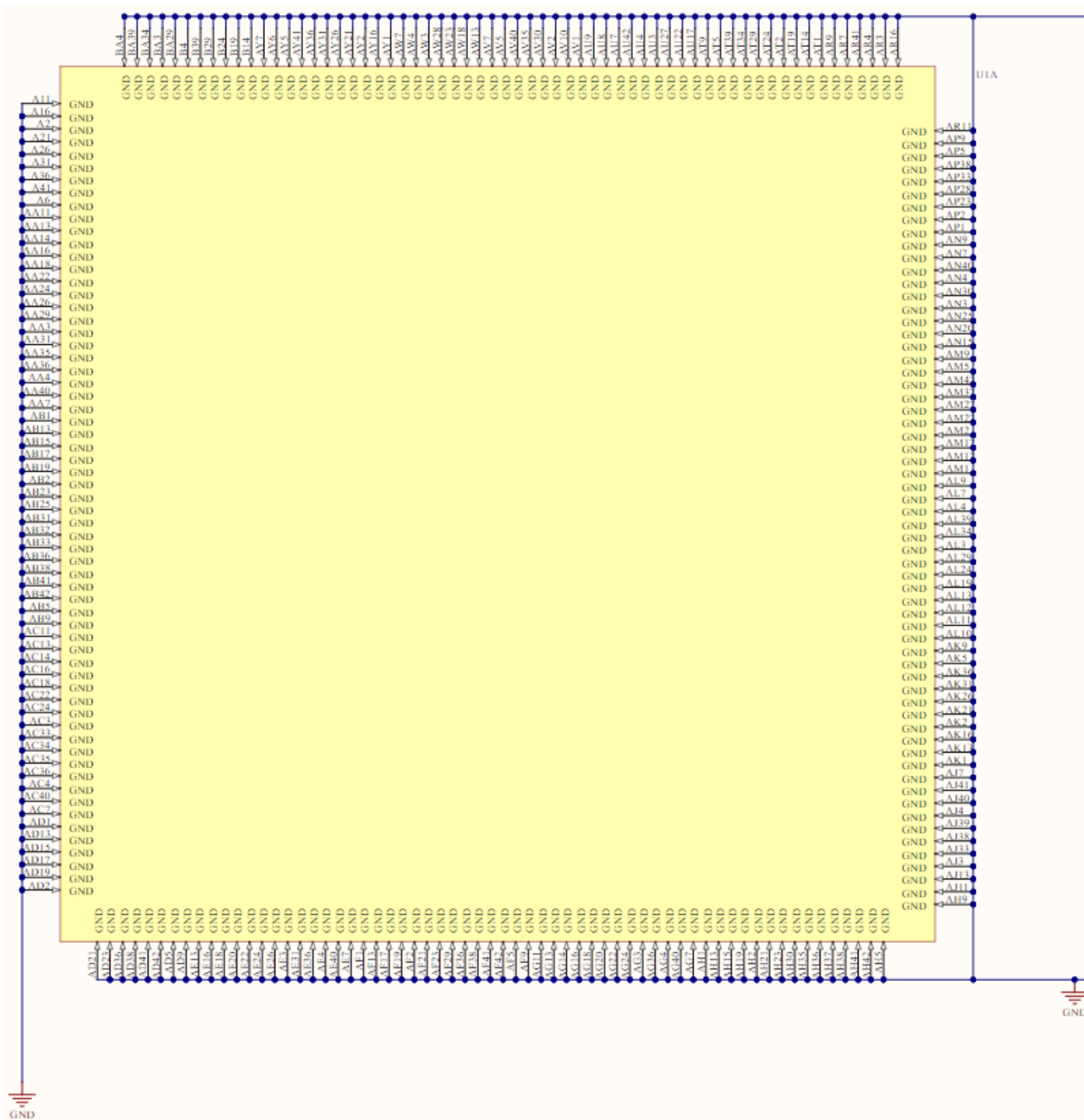
VCCINT_IO

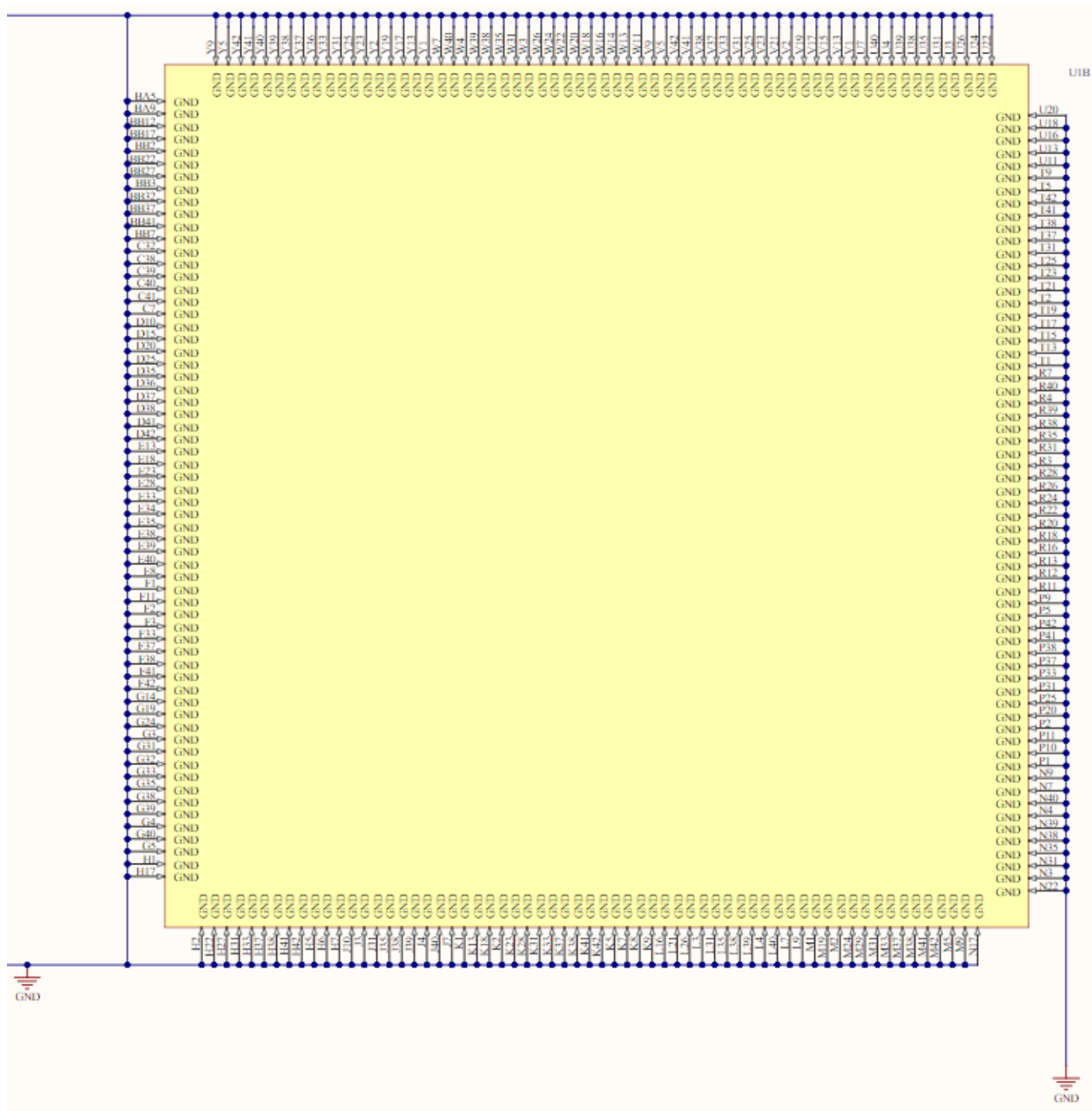


MGTAVCC









Availability

Xilinx part number	ProGrAnalog part number
ZU19-C1760	PA-KIT-ZU19-C1760

N America:

<https://www.mouser.com>

<https://www.avnet.com>

China:

<https://www.forenext.com>

EMEA:

<https://www.avnet.com>

Taiwan:

<https://www.forenext.com>

Visit us at:

<https://loadslammer.com>

Questions:

support@progranalog.com